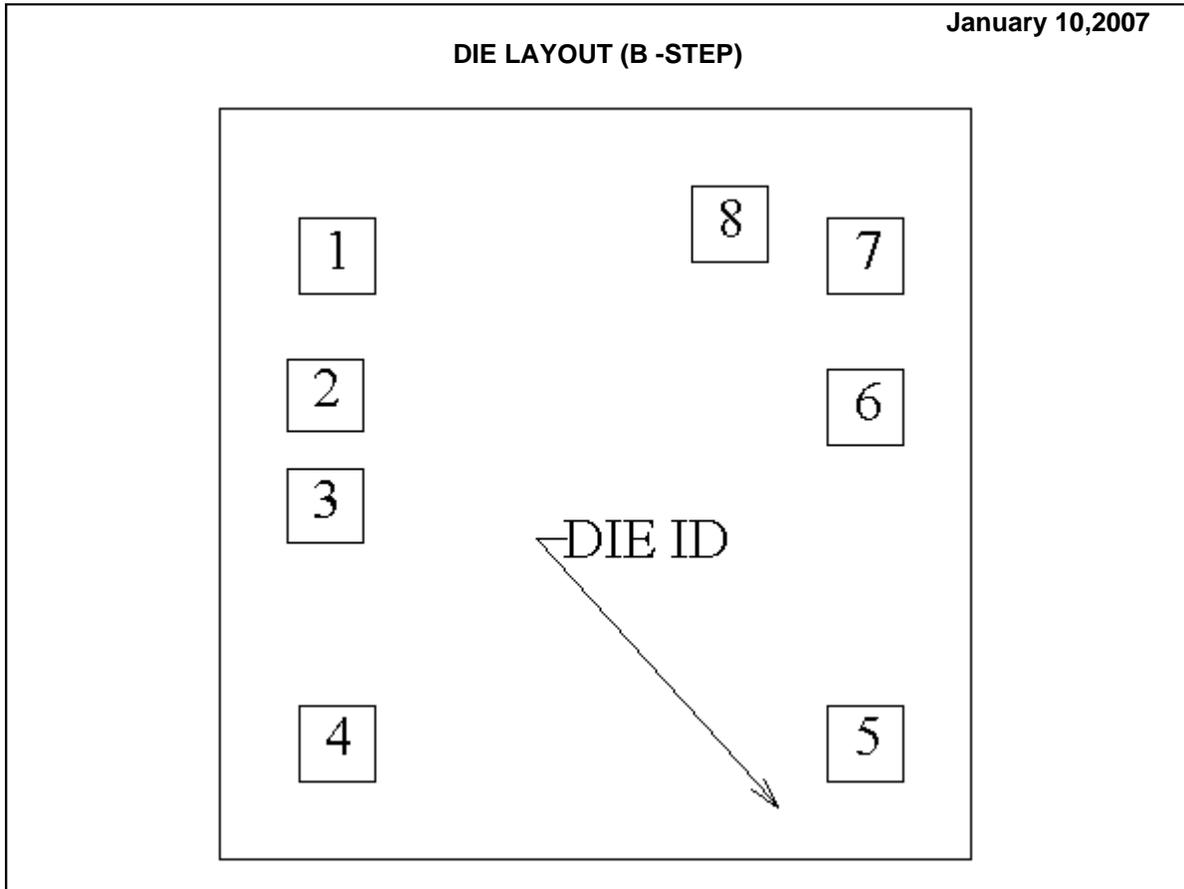


**CLC425 MDC MWC
ULTRA LOW NOISE WIDEBAND OP AMP**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	UB1703B	Bond Pad Opening Size (min)	100µm x 95µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	OXIDE OVER NITRIDE
Wafer Diameter	125mm	Back Side Metal	Bare Back
Die Size (Drawn)	1000µm x 1000µm 39.4mils x 39.4mils	Back Side Connection	Floating
Thickness	406µm Nominal		
Min Pitch	147µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
VIN-	1	-342	301	100	x	100
NC	2	-358	118	100	x	95
VCC-	3	-358	-29	100	x	100
VIN+	4	-342	-343	100	x	100
VOUT	5	358	-343	100	x	100
VCC+	6	358	101	100	x	100
RP	7	358	301	100	x	100
NC	8	177	343	100	x	100

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